



# "TRW CPUAX SuperChip"

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	Wafer-Scale Integration Approach
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## Introduction

### ► VHSIC Phase II Program

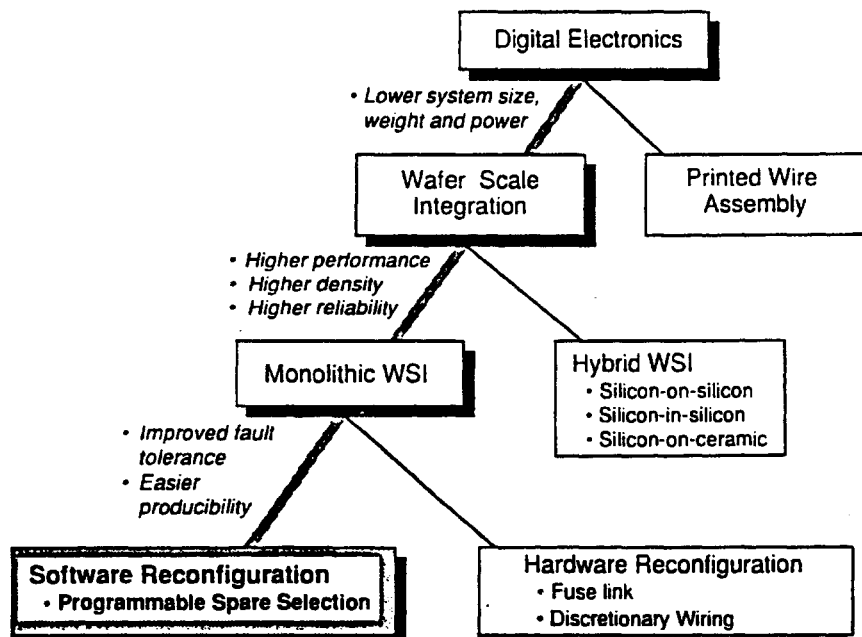
- 1985/1991 Start/Completion
- Motorola/TRW Team
- Submicron CMOS Technology
- Central Processor Unit - Arithmetic Extended (CPUAX) SuperChip
- Three Support Chips - Universal Processor, Microcontrol Unit & Bus Interface Unit

### ► Objectives

- Monolithic Wafer-Scale Integration
- 0.5 $\mu$ m CMOS Process
- 100 MHz Clock Rate
- Functional Throughput Rate  $10^{13}$  gate-Hz/cm<sup>2</sup>
- Built-In Self-Test (BIST)
- On-Chip Redundancy & Programmable Reconfigurability

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## Evolution Of Digital Electronics

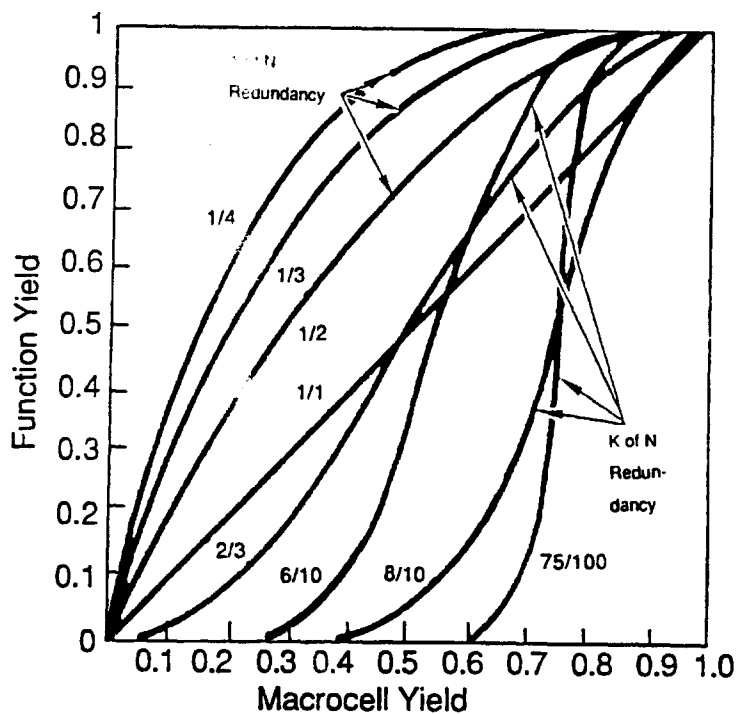


## Software Reconfigurable Monolithic WSI Approach

- ▶ **Redundant VLSI Sparing**
  - Macrocells are functional building blocks
  - Macrosets contain N macrocells
  - K of N macrocell sparing to provide high yield
- ▶ **Triple Modular Redundant (TMR) Interconnect**
  - Macrosets communicate through TMR interconnect
  - Logically equal wires separated and voted
- ▶ **Built-In Self-Test**
  - Initiates, controls, monitors macrocell and interconnect tests
  - Configures SuperChip at system power-up

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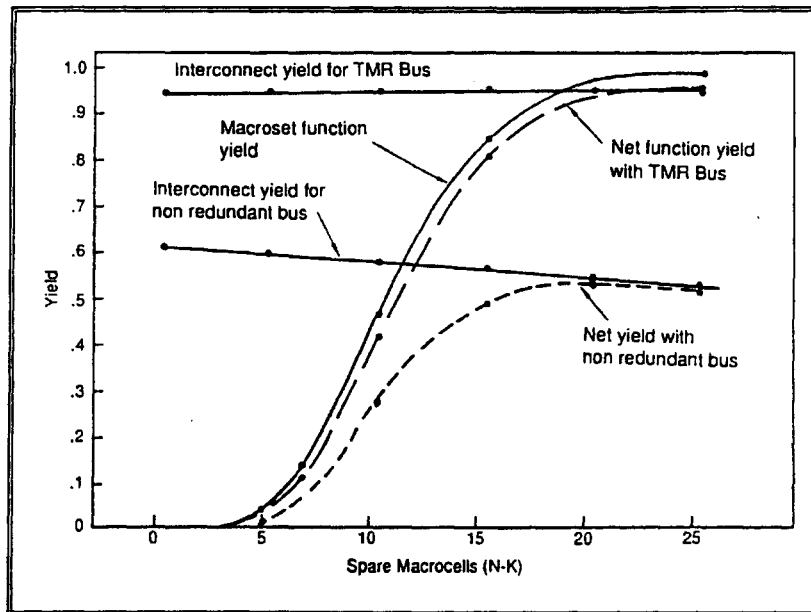
### K of N Macrocell Sparing



K - Number of macrocells in a macroset

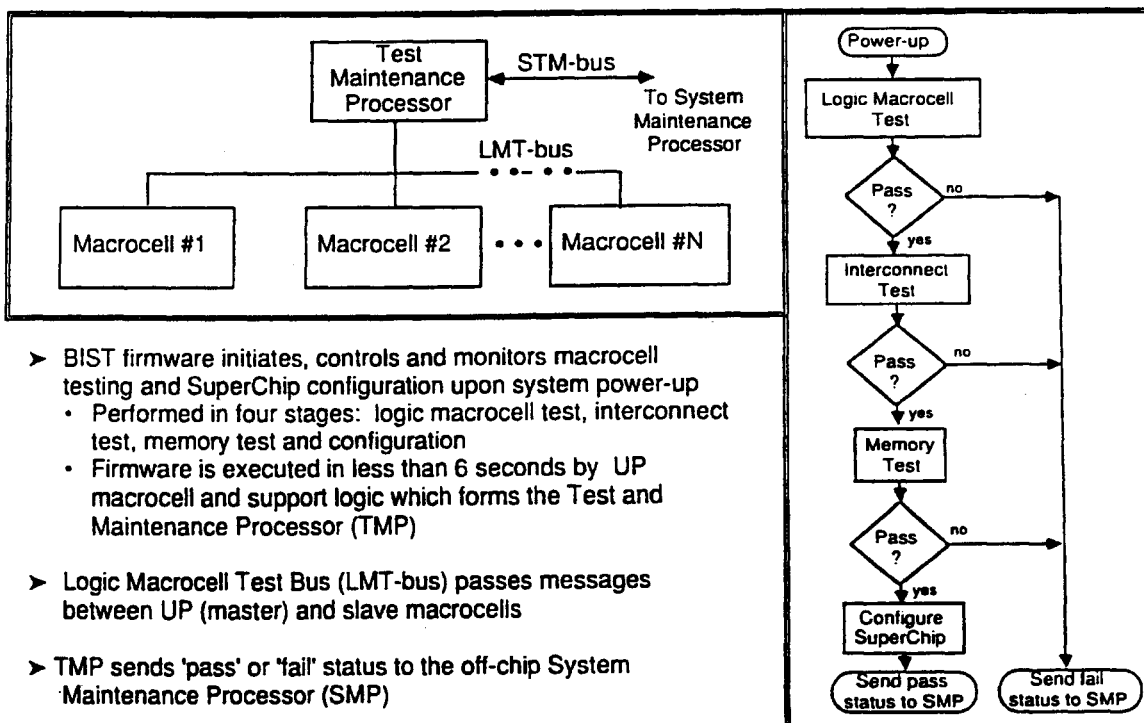
N - Minimum number of macrocells required for functionality

# Triple Modular Redundant Interconnect



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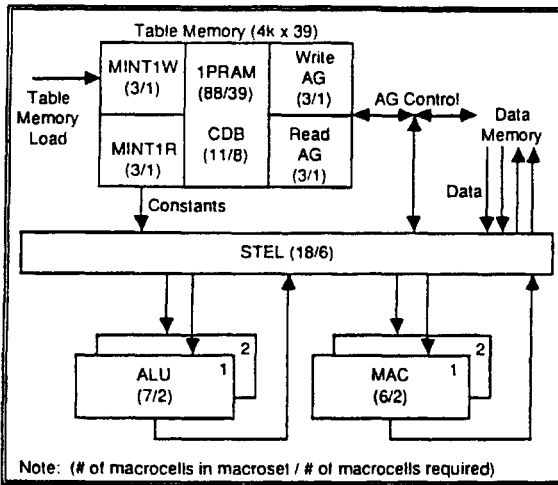
# Built-In Self-Test Features



- BIST firmware initiates, controls and monitors macrocell testing and SuperChip configuration upon system power-up
  - Performed in four stages: logic macrocell test, interconnect test, memory test and configuration
  - Firmware is executed in less than 6 seconds by UP macrocell and support logic which forms the Test and Maintenance Processor (TMP)
- Logic Macrocell Test Bus (LMT-bus) passes messages between UP (master) and slave macrocells
- TMP sends 'pass' or 'fail' status to the off-chip System Maintenance Processor (SMP)

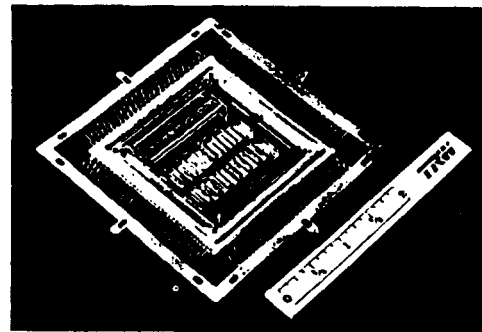
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## CPUAX SuperChip Features



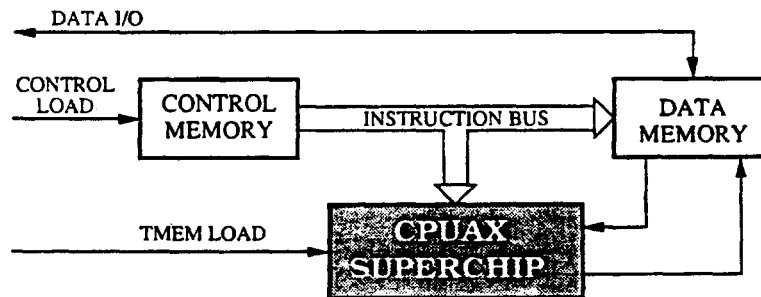
- Executes digital signal processing algorithms
  - Dual floating point ALUs
  - Dual floating point MACs } (MIL-STD-1750A format)
  - 4 KW x 39-bit table memory (32-bit data + 7-bit SECDED)
  - Six storage elements (each 16 words x 32 bits)
- 200 MFLOPS maximum throughput
- External interface to data memory
  - AG control with two 32-bit input and output ports
- Instruction code provided by external control memory
- Supports built-in self-test functions

- 0.5  $\mu$ m LOCOS CMOS
- 142 macrocells
  - 61 active macrocells (81 redundant)
  - 4.1 M devices with 1.7 M active
- 1.5 in. x 1.6 in. die size
- 8.5 W nominal power dissipation
- 275 I/O pins



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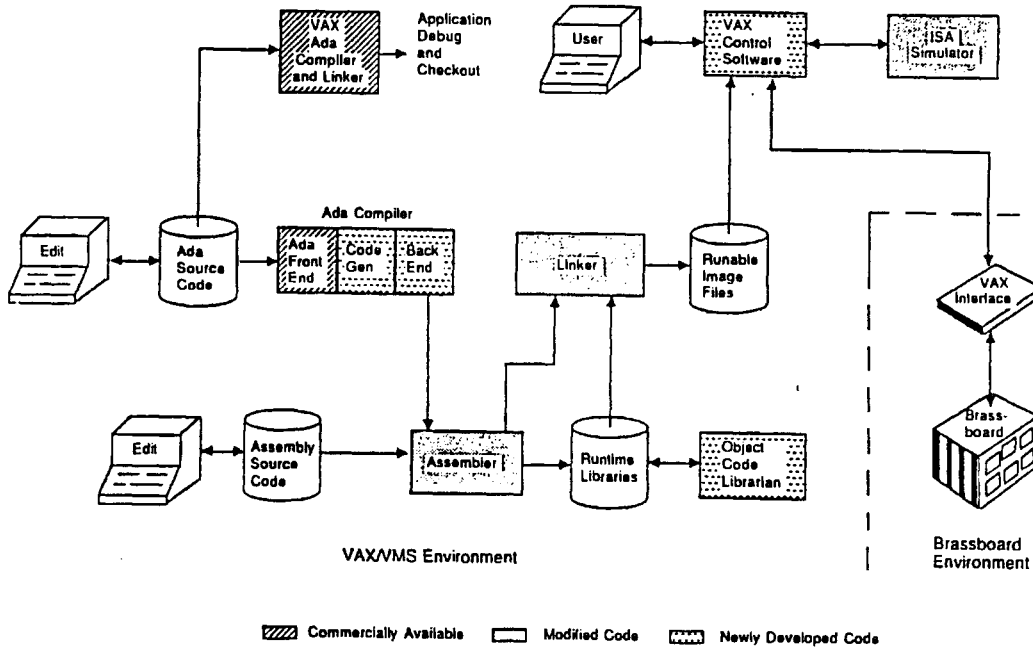
## CPUAX SuperChip System Architecture



- Typical CPU architecture with the CPUAX as the processing node
- CPUAX will support an I/O bandwidth of 200 million words per second (MWps)
  - Optimized for dual-port data memory

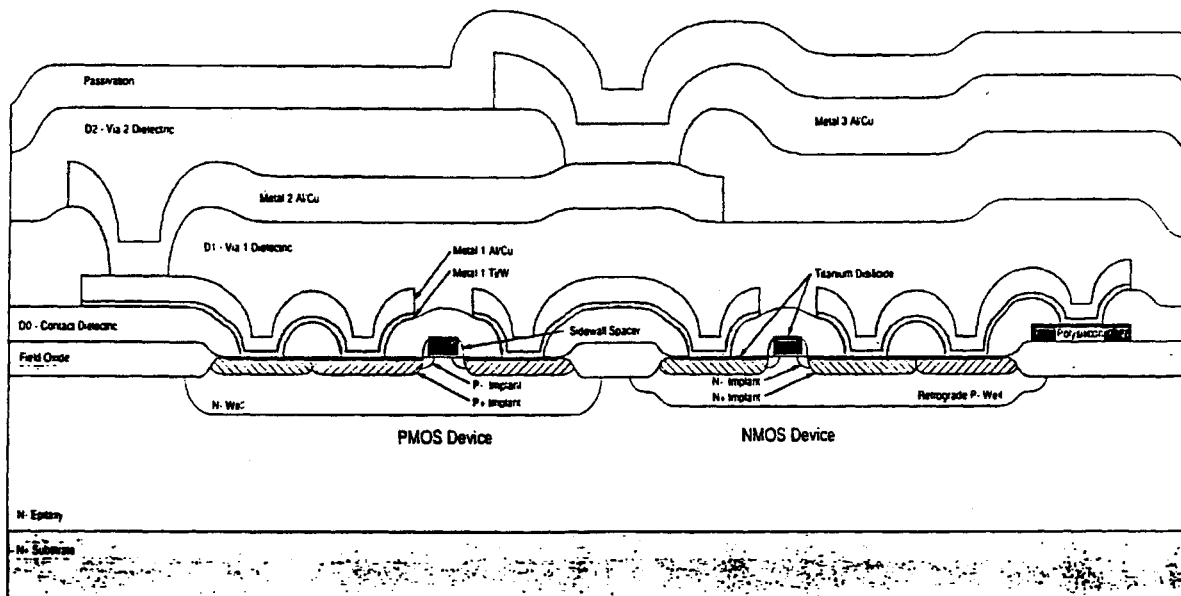
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## Support Software Environment

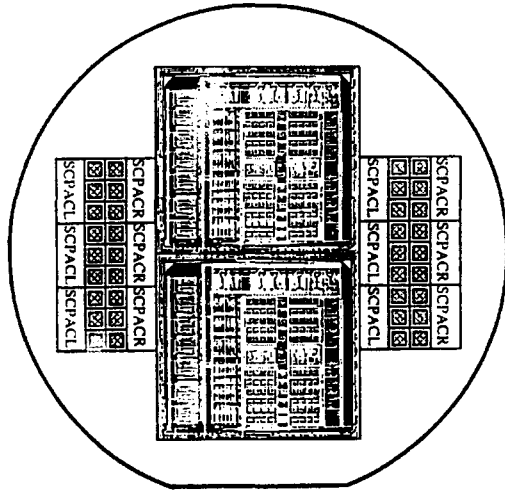


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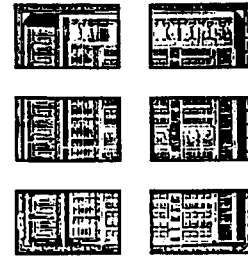
## 0.5μm CMOS Technology



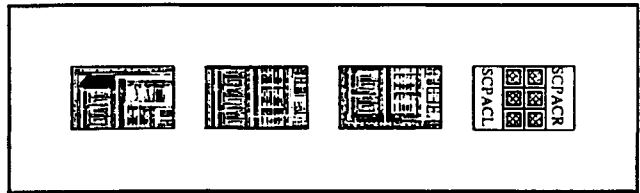
# CPUAX Fabrication Techniques



CPUAX Wafer Layout



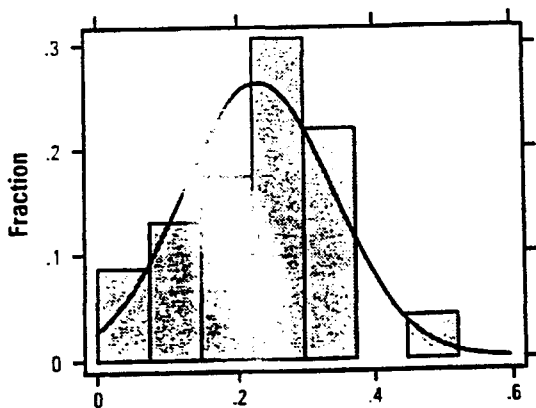
CPUAX Exposure Fields



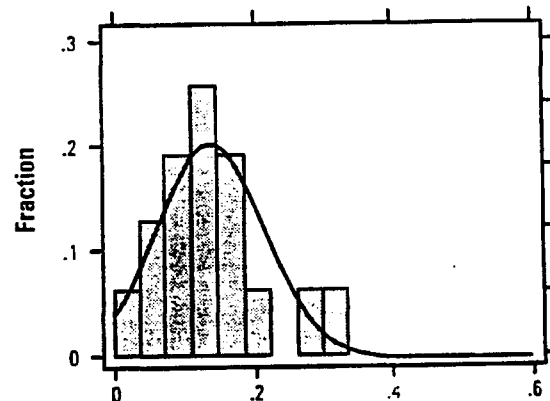
Ultratech 1500 Reticle

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# Optical Stepper Interfield Boundary Stitching Accuracy

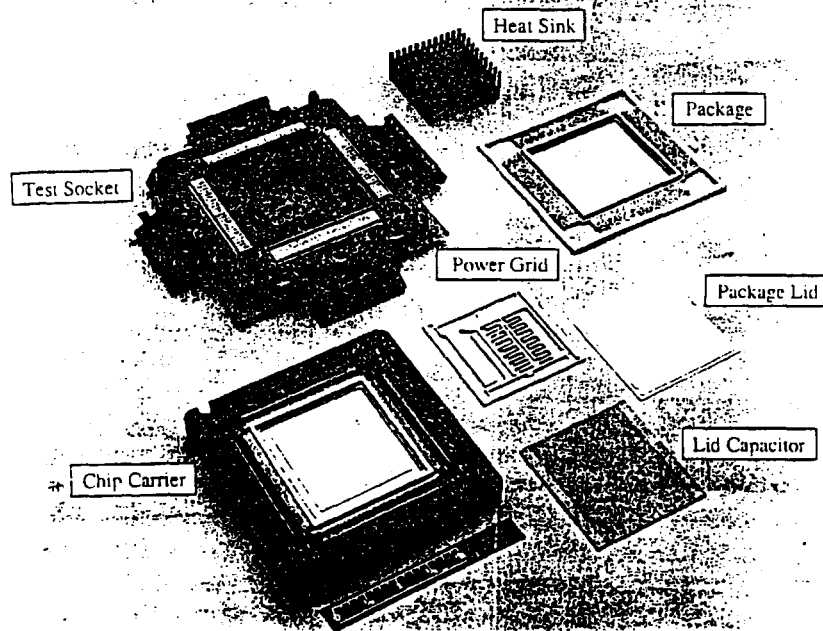


Horizontal error (µm)



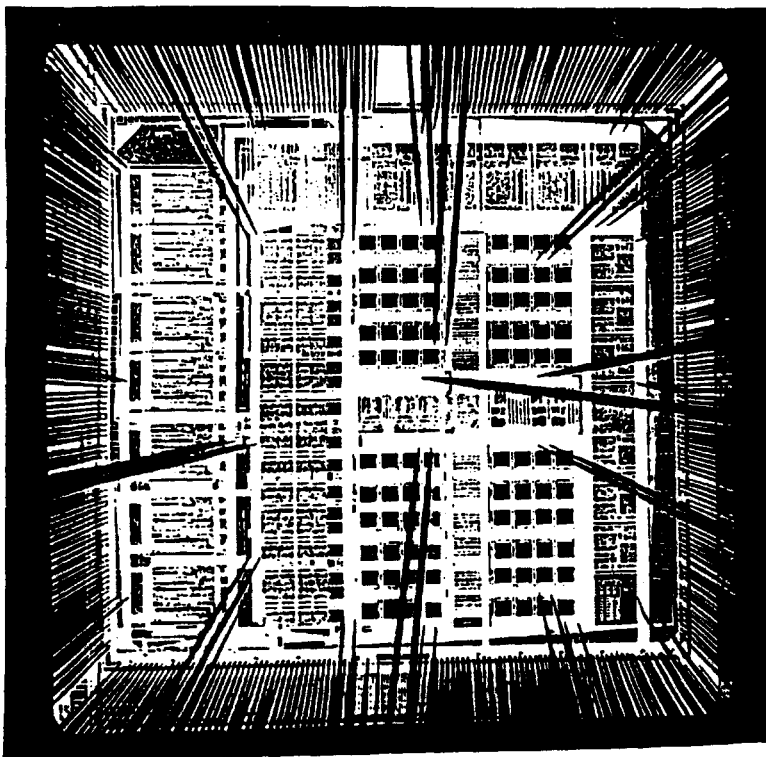
Vertical error (µm)

## CPUAX SuperChip Assembly



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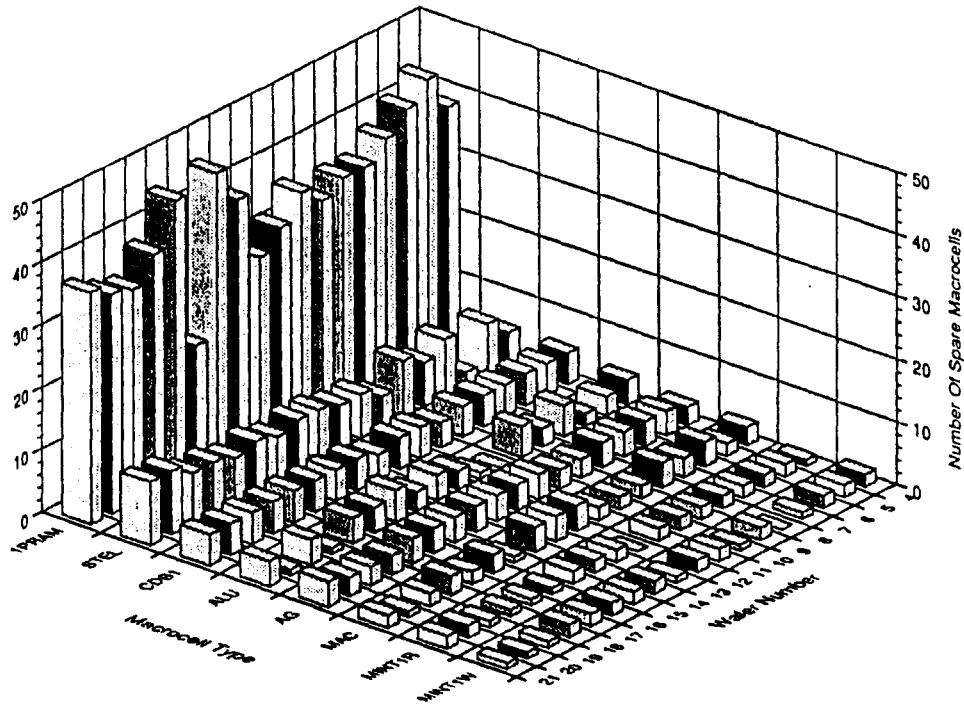
## CPUAX SuperChip Probe Test



- ▶ Custom Rucker & Kolls Probe Card
- ▶ 360 Pin Probe Card
  - 286 Signal Pins
  - 50 Edge Power/Ground Pins
  - 24 Internal Power/Ground Pins
- ▶ 4.8 x 4.8 cm Opening

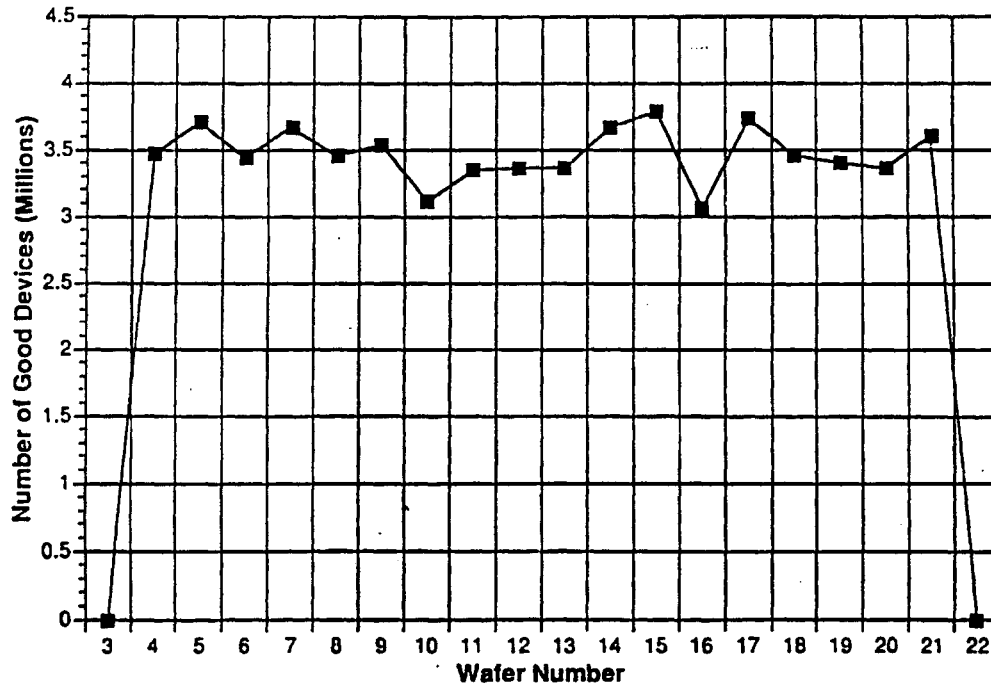


**Spare Macrocell Yield (Lot CX-4)**



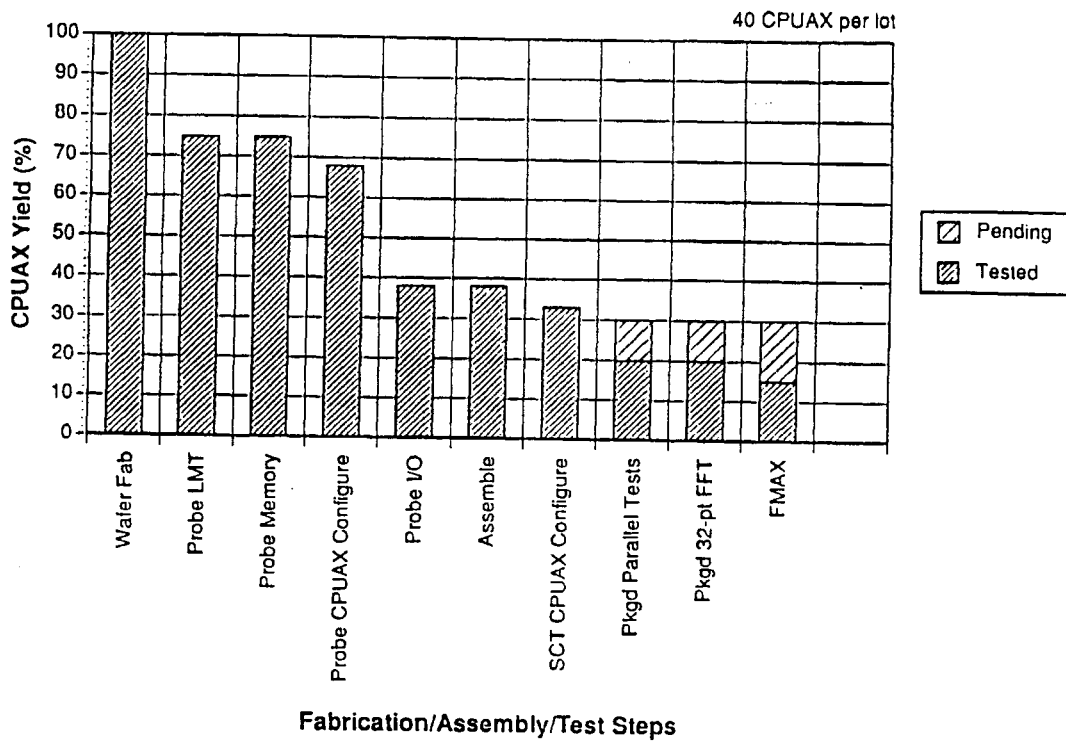
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**Cumulative Transistor Yield (Lot CX-4)**



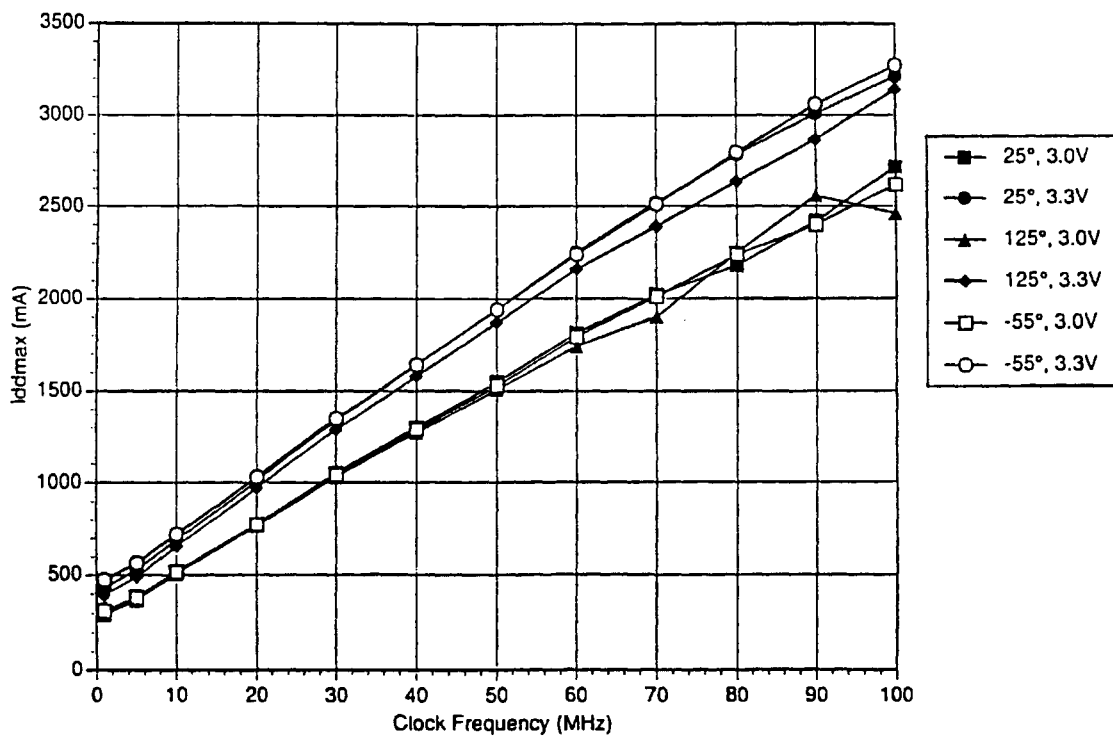
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## Pareto Yield Analysis (Lot CX-4)

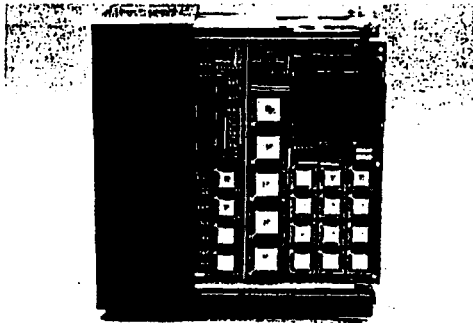


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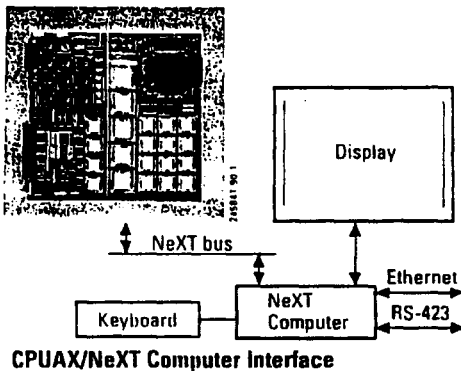
## CPUAX Power Performance (S/N 022)



# CPUAX Enables High Performance Signal Processor for NeXT Computer



NeXT Workstation



- CPUAX-based vector co-processor board
- Targeted at computationally intensive, high throughput signal processing applications
- Form, fit and function compatible with NeXT computer
- Provides hardware and application code development environment for CPUAX insertions

## Performance

- 50 million floating point operations per second at 25 MHz
- 32 bit floating point/24 bit integer with multiple precision support
- 256K byte scratch pad memory with dedicated read and write address generators
- 8M byte I/O buffer memory
- Microcontrol unit with 4K instruction memory
- On-board bootup/configuration logic

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## Summary

- ▶ Demonstrated the design of a software-reconfigurable monolithic wafer-scale integration circuit
- ▶ Developed a 0.5 $\mu$ m CMOS technology capable yielding high transistor count circuits (>1.5M) and sustaining high clock rates (100 MHz)
- ▶ CPUAX can provide high throughput (200 MFLOPs) for general purpose signal processing for a variety of system applications
- ▶ Yield enhancements can be made through improved macrocell spacing and control over single point induced failures in nonredundant I/O circuitry
- ▶ The CPUAX has been demonstrated as a coprocessor element in the NeXT computer work station